**征求意见反馈表**

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| 姓名 |  | 职称 |  | 手机 |  | 单位 |  |
| 标准名称 | | 半导体封装用金基键合丝及金扁线 | | | | | |
| 序号 | 标准章条编号 | | 意见内容 | | | | |
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